

PMP9455_BOM

COUNT	RefDes	Value	Description	Size	MFR
1	C1	1uF,10V	Capacitor, Ceramic Chip, 10V, ±10%	0603	STD
1	C2	100nF	Capacitor, Ceramic Chip, 50V, ±10%	0603	STD
1	C3	2.2uF,25V	Capacitor, Ceramic Chip, 25V, ±10%	0805	STD
1	C4	10uF,35V	Capacitor, Alum Electrolytic 35 V, ±20%	5.00 mm Dia	Nippon
1	C5	10uF,35V	Capacitor, Alum Electrolytic 35 V, ±20%	5.00 mm Dia	Nippon
1	C6	100nF	Capacitor, Ceramic Chip, 50V, ±10%	0805	STD
1	C7	470pF	Capacitor, Ceramic Chip, 50V, ±10%	0603	STD
1	C8	470pF	Capacitor, Ceramic Chip, 50V, ±10%	0603	STD
1	C9	470pF	Capacitor, Ceramic Chip, 50V, ±10%	0603	STD
1	C10	470pF	Capacitor, Ceramic Chip, 50V, ±10%	0603	STD
1	D1	1N4148	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-81	Vishay
1	D2	1N4148	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-81	Vishay
1	D3	1N4148	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-81	Vishay
1	D4	1N4148	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-81	Vishay
1	D5	TZM5242B,12V	Diode, Zener, 12V, 500mW	SOD-81	Vishay
1	D6	TZM5231B,5.1V	Diode, Zener, 5.1V, 500mW	SOD-81	Vishay
1	D7	TZM5232B 5.6V	Diode, Zener, 5.6V, 500mW	SOD-81	Vishay
1	J1	SIP 14 PIN	SIP Connector		STD
1	Q1	BC847	Trans, G.P. Nch, 45/-45V, 100mA,	SOT-23	NXP
1	R1	470E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R2	470E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R3	470E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R4	470E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R5	4.7K	Resistor, Chip, 1/16W, 1%	0603	Std
1	R6	4.7K	Resistor, Chip, 1/16W, 1%	0603	Std
1	R7	4.7K	Resistor, Chip, 1/16W, 1%	0603	Std
1	R8	4.7K	Resistor, Chip, 1/16W, 1%	0603	Std
1	R9	10E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R10	10E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R11	10E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R12	10E	Resistor, Chip, 1/16W, 1%	0603	Std
1	R13	100K	Resistor, Chip, 1/16W, 1%	0603	Std
1	R14	10K	Resistor, Chip, 1/16W, 1%	0603	Std
1	R15	33E, 0.25W	Resistor, Chip, 1/4W, 1%	0805	Std
1	R16	330E,0.25W	Resistor, Chip, 1/4W, 1%	0805	Std
1	U1	SM72295MA	IC, Photovoltaic Full Bridge Driver	SO-28	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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